

WHAT IS CLAIMED IS:

1. A package structure for a hybrid optical module, comprising:

components for detecting an optical signal, excluding an objective lens;

a hollow resin package which houses said components for detecting an optical signal; and

a metal frame a portion of which is mounted on said resin package, said components for detecting an optical signal being bonded onto said mounted portion, and another portion of which is vertically bent in accordance with a shape of said resin package and embedded into said resin package.

2. A package structure for a hybrid optical module according to claim 1, wherein said components for detecting an optical signal constitute an optical pickup unit.

3. A package structure for a hybrid optical module according to claim 1, wherein said metal frame is independently disposed for each of laser devices which are to be bonded.

4. A package structure for a hybrid optical module according to claim 1, wherein said metal frame radiates heat via said resin package to a metal part disposed outside said resin package.

5. A package structure for a hybrid optical module according to claim 1, wherein an end portion of said metal frame is led out from said resin package, and made in contact with a metal part disposed outside said resin package.

6. A method of producing a package structure for a hybrid optical module, said package comprising: a hollow resin package which houses components for detecting an optical signal, excluding an objective lens; and a metal frame a portion of which is mounted on said resin package, and onto which said components for detecting an optical signal are to be bonded, wherein said method comprises the steps of:

vertically bending another portion of said metal frame in accordance with a shape of said resin package;

embedding said other portion of said metal frame into said resin package, and then performing a shaping process; and

bonding said components for detecting an optical signal onto said portion of said metal frame.